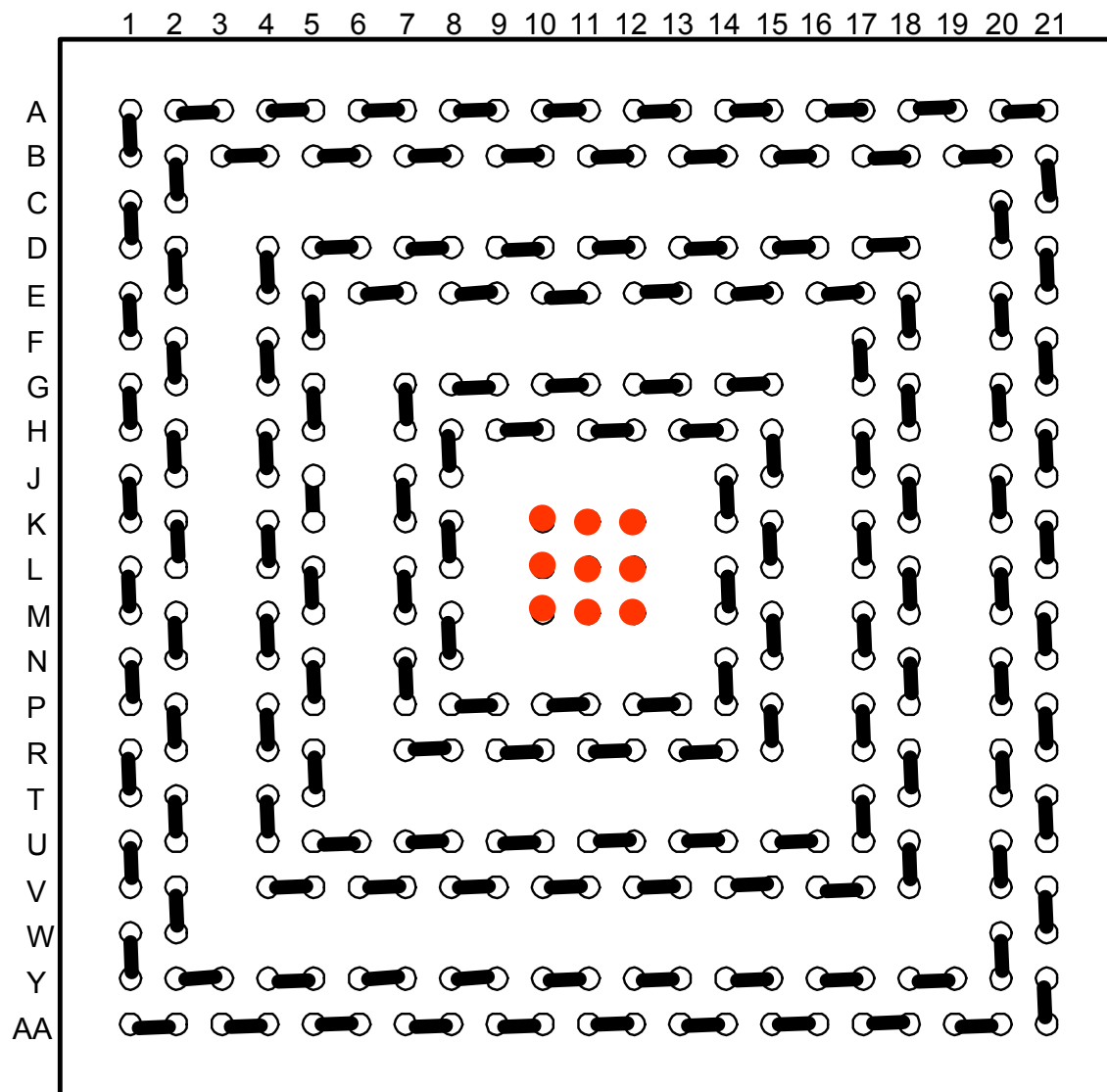




Chain Package Design

15mm, 321 MAP BGA, 0.65mm Pitch



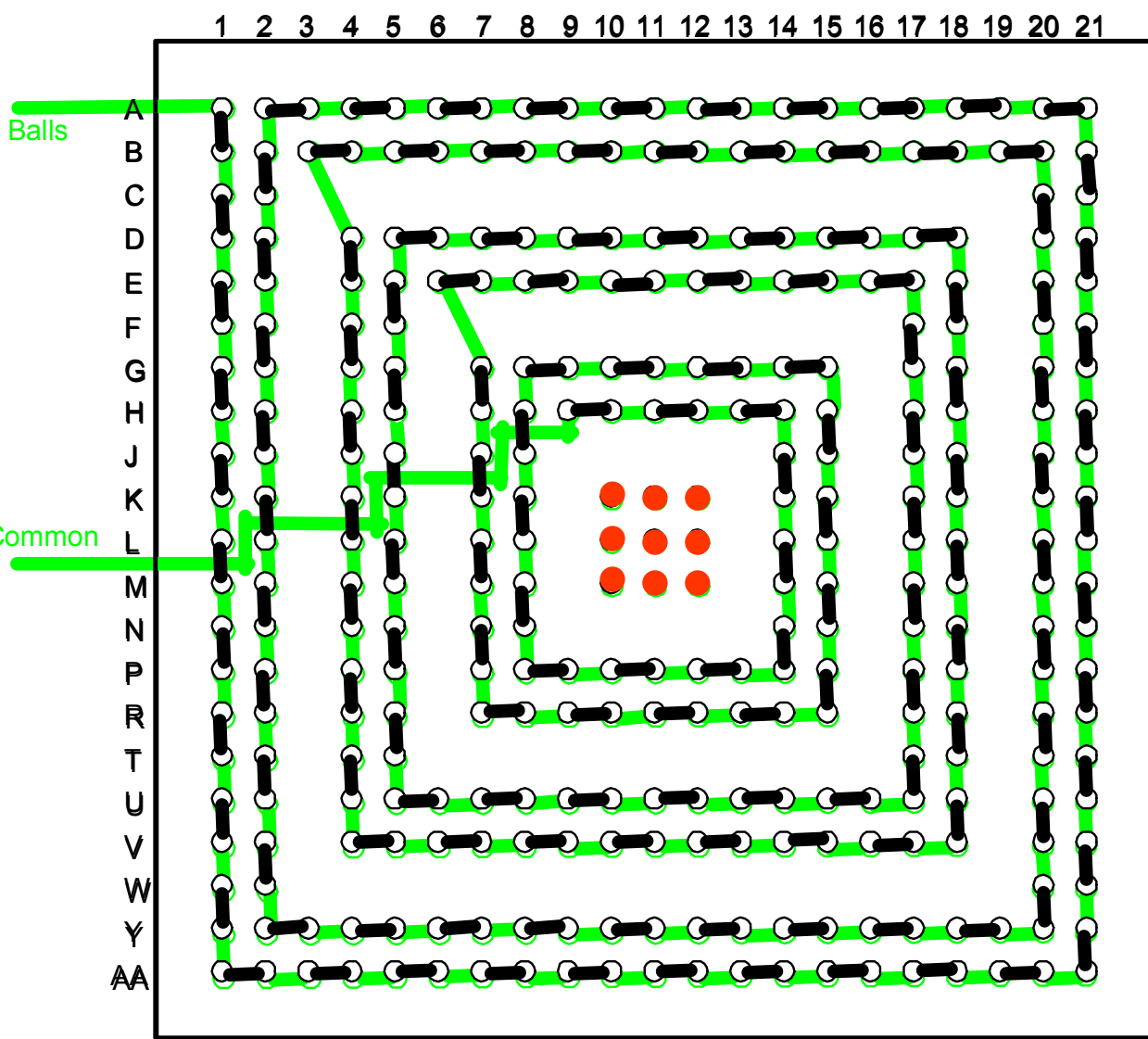
- * 0.65 mm Pitch
- * 21x21 Array
- * 9 Thermal Balls
- * 15x15 mm Body Size
- * 0.3 mm Solder Ball Diameter

- = Suggested Test Board Trace
- = BGA Package Trace
- = Do not connect these pads.
Freescale Internal Use Only.

Slide 1

NXP Chain Test Board Design

15mm, 321 MAP BGA, 0.65mm Pitch



- * 0.65 mm Pitch
- * 21x21 Array
- * 9 Thermal Balls
- * 15x15 mm Body Size
- * 0.3 mm Solder Ball Diameter

- = Suggested Test Board Trace
- = BGA Package Trace
- = Do not connect these pads.
Freescale Internal Use Only.